



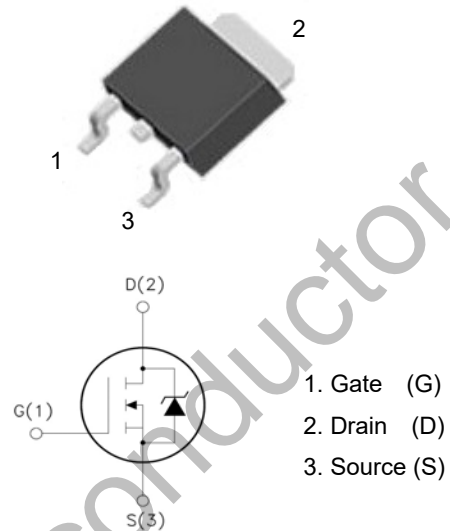
WGD15N10

100V N-Channel MOSFET

Features:

- Low Intrinsic Capacitances.
- Excellent Switching Characteristics.
- Extended Safe Operating Area.
- Unrivalled Gate Charge :Qg= 15.6nC (Typ.).
- BVDSS=100V, I_D=15A
- R_{DS(on)} : 0.9Ω (Max) @V_G=10V
- 100% Avalanche Tested

TO-252



Electrical Characteristics (TA =25°C Unless Otherwise Specified)

Symbol	Parameter	Rating	Unit	
V(BR)DSS	Drain-Source breakdown voltage	100	V	
VGS	Gate-Source voltage	±20	V	
ID	Continuous drain current@VGS=10V	T _C =25°C	15	A
		T _C =70°C	9.6	A
IDM	Pulse drain current tested ①	T _C =25°C	40	A
PD	Maximum power dissipation	T _C =25°C	30	W
IS	Diode Continuous Forward Current	T _C =25°C	17	A
IAS	Avalanche Current Max	L=0.5mH	11	A
EAS	Avalanche energy, single pulsed ②		9	mJ
TSTG,TJ	Storage and operating temperature range		-55 to 175	°C
R JA	Thermal Resistance Junction-Ambient		60	°C/W
R JC	Thermal Resistance-Junction to Case		5	°C/W

Static Electrical Characteristics @ T_J = 25°C (unless otherwise stated)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V ID=250μA	100	--	--	V
IDSS	Zero Gate Voltage Drain Current(Tc=25°C)	V _{DS} =100V,V _{GS} =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(Tc=125°C)	V _{DS} =100V,V _{GS} =0V	--	--	100	μA
IGSS	Gate-Body Leakage Current	V _{GS} =±20V,V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} ,ID=250μA	1.0	1.6	2.2	V
R _{DS(ON)}	Drain-Source On-State Resistance③	V _{GS} =10V, ID=10A	--	85	90	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance③	V _{GS} =4.5V, ID =5A	--	95	100	mΩ

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated)

C _{iss}	Input Capacitance	V _{DS} =30V,V _{GS} =0V, f=1MHz	--	525	--	pF
C _{oss}	Output Capacitance		--	41	--	pF
C _{rss}	Reverse Transfer Capacitance		--	36	--	pF
R _g	Gate Resistance		--	2.6	--	
Q _g	Total Gate Charge		--	15.6	--	nC
Q _{gs}	Gate-Source Charge	V _{DS} =50V,ID=3A, V _{GS} =10V	--	3.2	--	nC
Q _{gd}	Gate-Drain Charge		--	4.4	--	nC

Switching Characteristics

t _{d(on)}	Turn-on Delay Time	V _{DD} =50V, ID=1A, R _G =6.8 , V _{GS} =4.5V	--	8	--	nS
t _r	Turn-on Rise Time		--	4.5	--	nS
t _{d(off)}	Turn-Off Delay Time		--	26	--	nS
t _f	Turn-Off Fall Time		--	3.8	--	nS

Source- Drain Diode Characteristics@ T_J = 25°C (unless otherwise stated)

V _{SD}	Forward on voltage	I _{SD} =10A,V _{GS} =0V	--	0.89	1.20	V
t _{rr}	Reverse Recovery Time	T _J =25°C,I _{sd} =10A, V _{GS} =0V di/dt=500A/μs	--	26	--	nS
Q _{rr}	Reverse Recovery Charge		115	--	--	nC

NOTE:

1. Repetitive rating; pulse width limited by max. junction temperature
2. Limited by T_{Jmax}, starting T_J = 25°C, L = 0.5mH,R_G = 25, I_{AS} = 6A, V_{GS} = 10V. Part not recommended for use
3. above this value. ③ Pulse width ≤ 300μs; duty cycle ≤ 2%.

Typical Characteristics

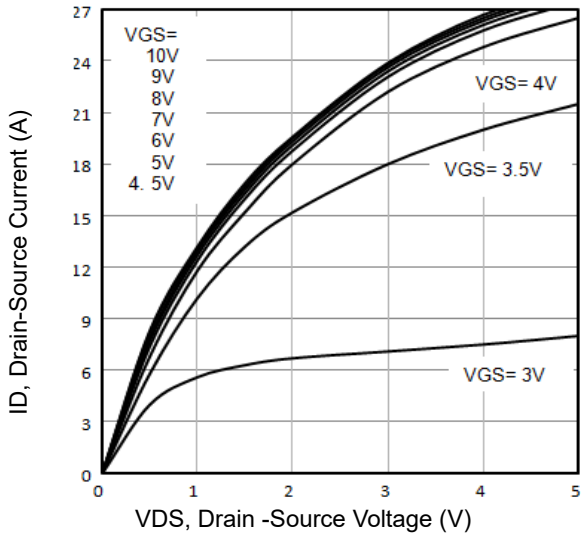


Fig1. Typical Output Characteristics

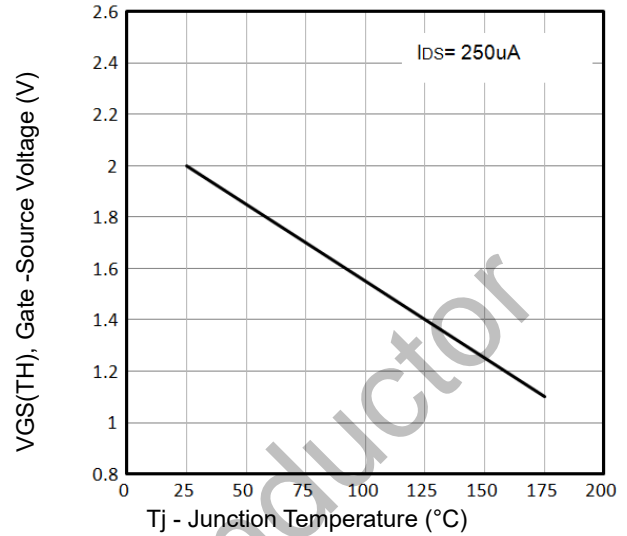


Fig2. $V_{GS(TH)}$ Gate-Source Voltage Vs. T_j

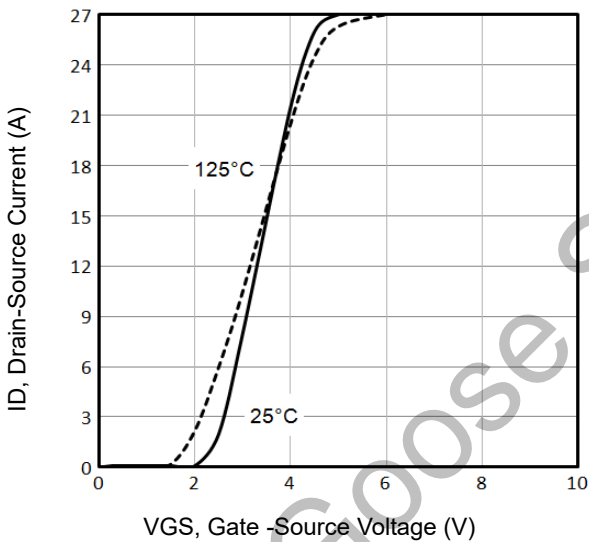


Fig3. Typical Transfer Characteristics

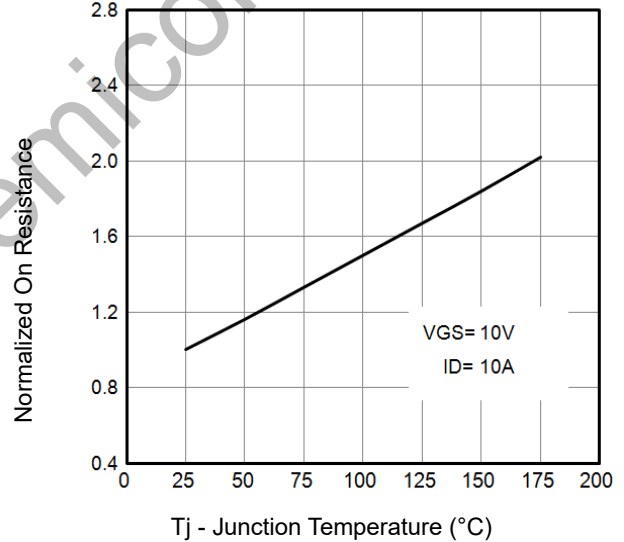


Fig4. Normalized On-Resistance Vs. T_j

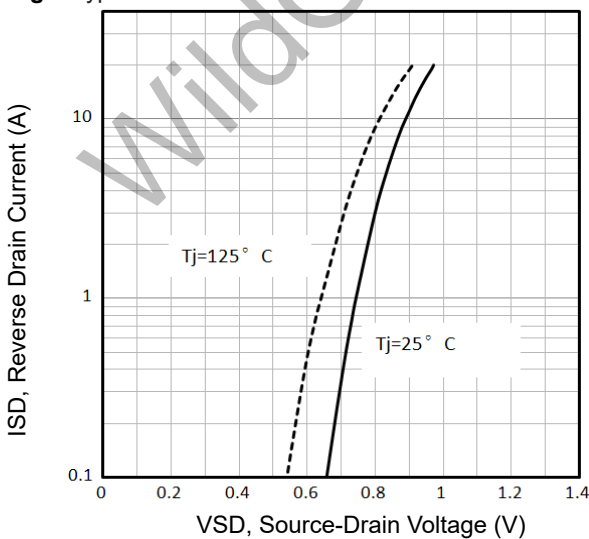


Fig5. Typical Source-Drain Diode Forward Voltage

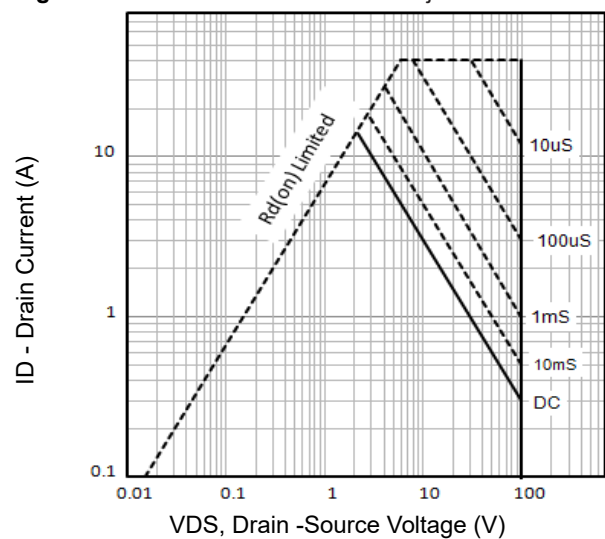


Fig6. Maximum Safe Operating Area

Typical Characteristics (Continued)

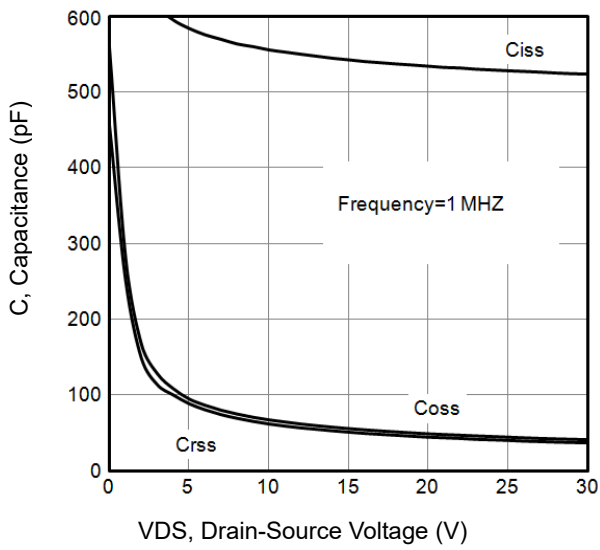


Fig7. Typical Capacitance Vs. Drain-Source Voltage

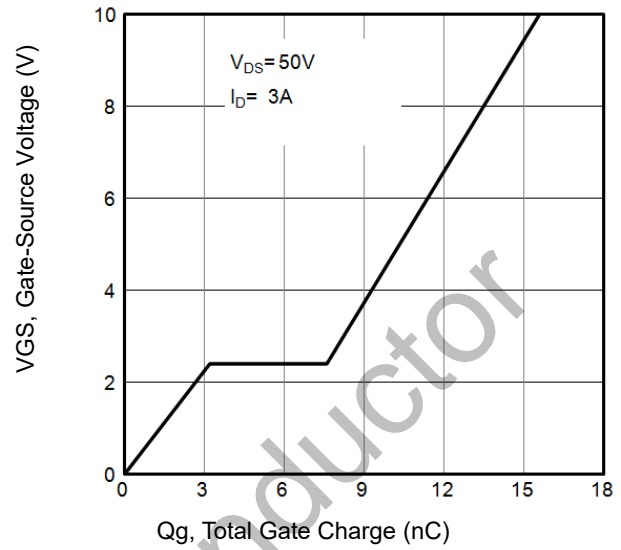


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

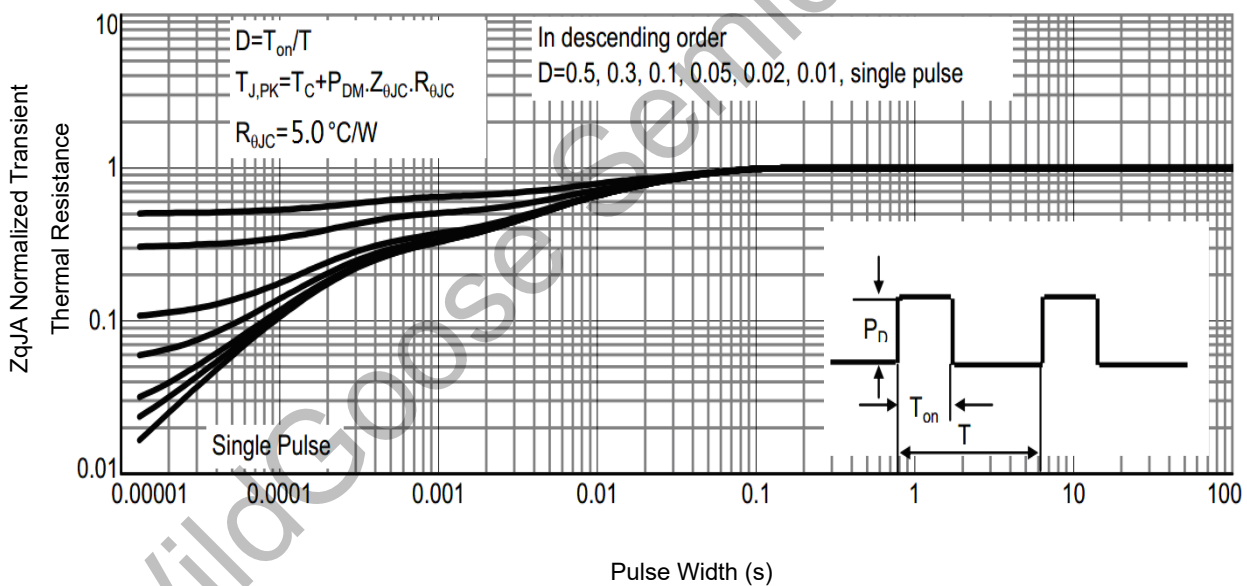
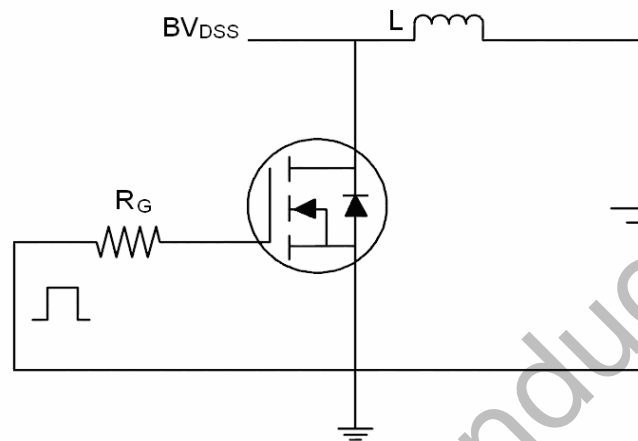


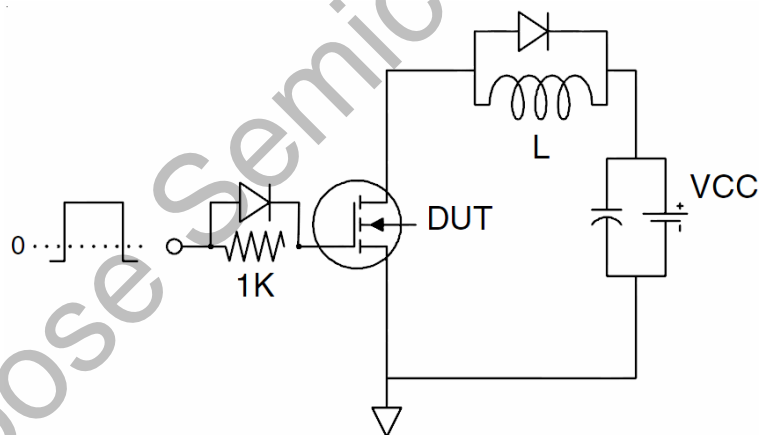
Fig9. Normalized Maximum Transient Thermal Impedance

Test Circuit

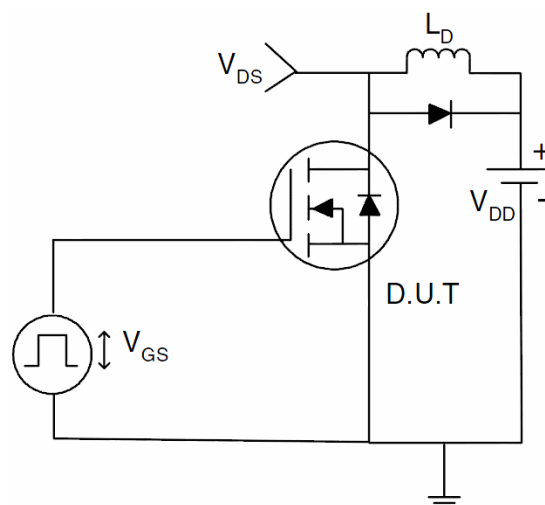
1) E_{AS} test Circuit



2) Gate charge test Circuit

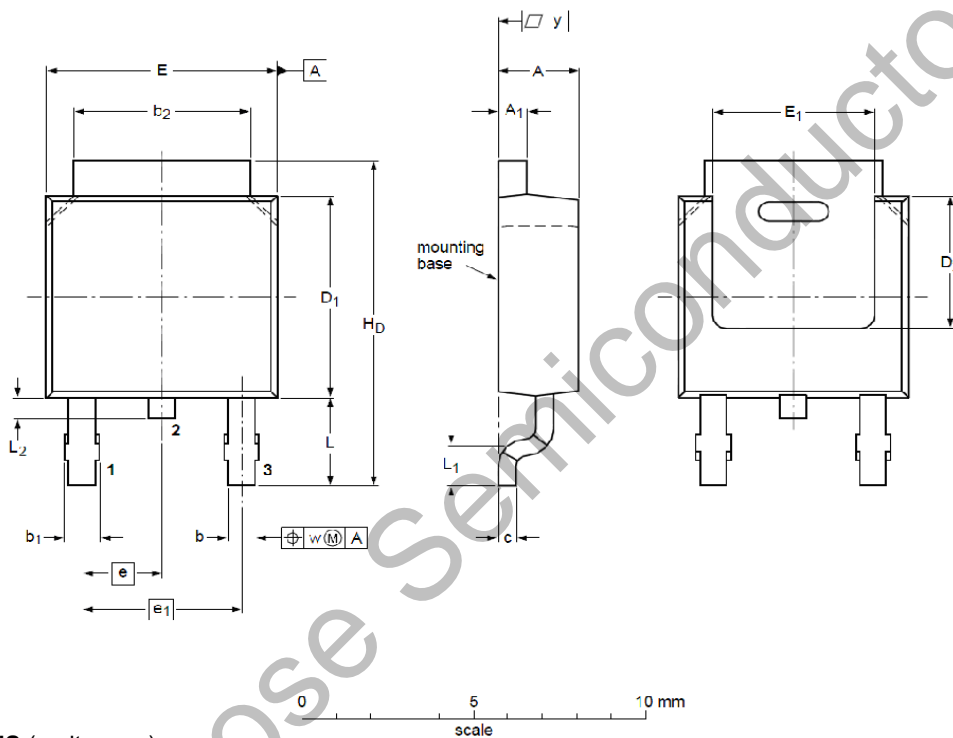


3) Switch Time Test Circuit



Package Dimension

TO-252



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.22	2.30	2.38	A ₁	0.46	0.58	0.93
b	0.71	0.79	0.89	b ₁	0.90	0.98	1.10
b ₂	5.00	5.30	5.46	c	0.20	0.40	0.56
D ₁	5.98	6.05	6.22	D ₂	--	4.00	--
E	6.47	6.60	6.73	E ₁	5.10	5.28	5.45
e	--	2.28	--	e ₁	--	4.57	--
H _b	9.60	10.08	10.40	L	2.75	2.95	3.05
L ₁	--	0.50	--	L ₂	0.80	0.90	1.10
w	--	0.20	--	y	0.20	--	--